ONLY FOR REFERENCE

Standard Spec Sheet

Mitsumi Model Name	SOV-169HST
Mitsumi Model No.	R 66 7844
Operating Force	3.5N
Pcs/Reel	5,000

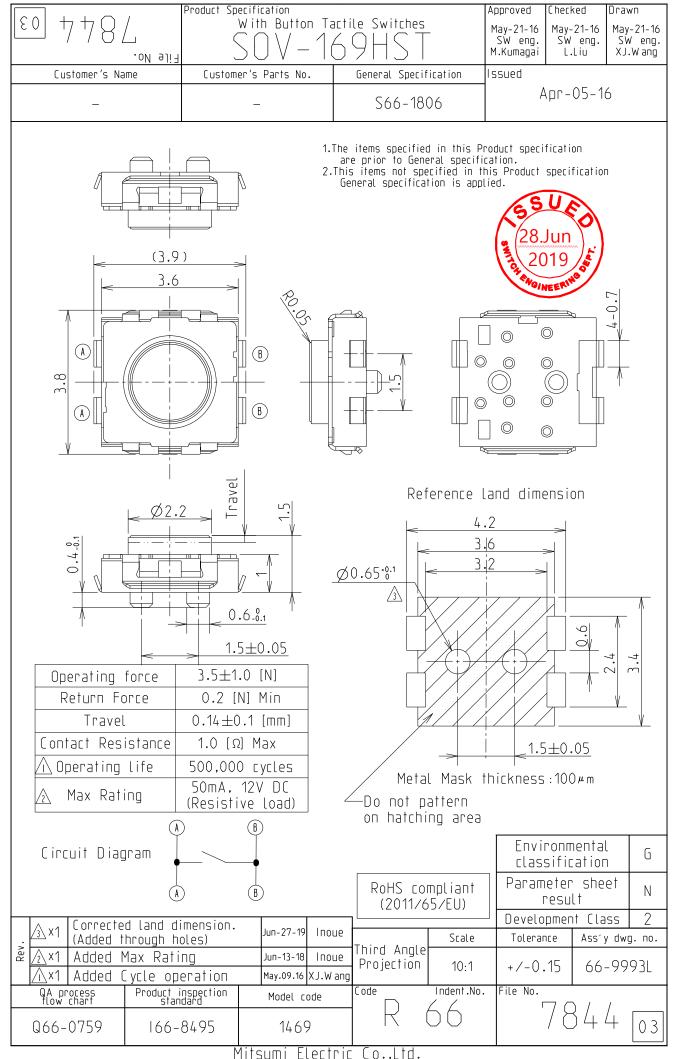
This specification is only for reference. If you have any questions for the details, please contact SW engineering division.

For your adopting the products, the formal supply specification will be provided.

MITSUMI ELECTRIC CO.,LTD.

2-11-2, Tsurumaki, Tama-shi. Tokyo 206-8657 Japan.

SWITCH ENGINEERING SECTION 1049, Tateiwa, Iizuka-shi. Fukuoka 820-8533 Japan.



908L

General specification Tactile switches

| |

Approved

Mar. 30.'16 SW eng. Kumagai Mar. 30.'16 SW eng. Lei.Liu Drawn

Mar. 30.'16

SW eng.

XinJian.Wang

SOV series

Released Mar. 30. '16

Checked

1. General

1.1. Application

This specification is applied to Tactile switches named SOV series.

1.2. Operating temperature range: -40 to +60 deg-C

1.3. Storage temperature range: -25 to +85 deg-C (Product level)

-20 to +50 deg-C (Taped condition)

1.4. Test conditions

Normal temperature; 5 to 35 deg-C, normal humidity; 45 to 85% RH. If any doubt arises from judgement, tests and measurements shall be conducted under the following conditions.

Temperature 20+/- 2deg-C, humidity 65+/-5% RH, and air pressure 86 to 106 kPa.

2. Appearance and Construction

2.1. Dimensions: Specified on Product specifications.

2.2. Materials: Refer to Table-1.

2.3. Appearance: There shall be no defects that affect the performance of

the products such as crack, scratch, dirt, discoloration,

and contamination.

2.4. Cross section view:

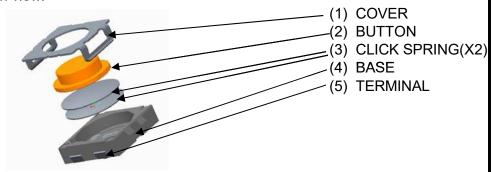


Fig. 1: Cross section of product

Table-1

Components	Material	Note
(1) COVER	Stainless steel	
(2) BUTTUN	6T Nylon	
(3) CLICK SPRING	Stainless steel	Ni+Ag plated
(4) BASE	6T Nylon	
(5) TERMINAL	Phosphor bronze	Ag plated

3. Rating

Specified on Product specification.



			Code	Division	File No.
ision					
_			0	66	1006
Re/			3	66	1806

Item	Test conditions	Criteria
4.1. Contact resistance	Measurements shall be made under the conditions shown in Fig. 3. 1) Load: 2 times of the specified standard operating force. 2) Measurement conditions: Contact resistance meter at 20 mV Max. and 50 mA Max. dia. 4.0 mm Push direction O.5 mm Max. Tilt angle 90+/-2 deg Misalianment 90+/-2 deg Flat tip Fig. 2: Push rod Fig. 3: Measurement conditions	Specified on Product specifications.
4.2. Insulation resistance	Measurements shall be made under the following conditions. 1) Applied voltage: 100 V, DC 2) Duration: 1 min. 3) Applied position: Between terminals.	10 M-ohm Min.
4.3. Withstanding voltage	Measurements shall be made under the following conditions. 1) Applied voltage: 100 V, AC (50/60 Hz) 2) Duration: 1 min. 3) Leak current: 2 mA 4) Applied position: Between terminals.	There shall be no damage and breakdown.
4.4. Bounce	Measurements shall be made under the conditions shown in Fig. 3. Bounce time at "ON" and "OFF" shall be measured under the following conditions. 1) Circuit: Refer to Fig. 4. 2) Load: 1.5 times of the specified standard operating force. 3) Frequency of operation: 3 to 4 times/sec. DC5 V SW 5 k-ohm Oscilloscope Fig. 4: Circuit	ON bounce: 10 ms Max. OFF bounce: 10 ms Max.
	"OFF" "ON bounce" Fig. 5: Bounce	SULTO 11.May 2016 ADJUNEERING

File number 1806

Item	Test conditions	Criteria			
5.1.	Measurements shall be made under the conditions shown in	Specified on			
Operating	Fig. 3 just after striking 10 times lightly.	Product			
force	1) Measurement speed: 0.5 mm/sec.	specifications.			
	2) Limit load to apply: 1.5 to 2 times of the specified	'			
5.2.					
Return					
force	Force (N)				
	Operating force				
	Return force				
	> Stroke (mm)				
	Fig. 6: Force-Stroke curve				
	ĭ				
5.3.	Refer to 5.1 and 5.2 for the measurement conditions.	Specified on			
Click ratio		Product			
	Force (N)	specifications.			
		'			
	> Stroke (mm)				
	Travel				
	Fig. 7 Force-Stroke curve				
5.4.	Measurements shall be made under the conditions shown in	There shall be			
Stopper	Fig. 3 and at returned condition.	no electrical			
strength	Load: 30 N	and mechanica			
J	Duration: 15 sec.	abnormality.			
		,			
5.5.	Measurements shall be made after testing under the	1			
Impact	following conditions.				
resistance	1) Acieration: 735 m/s ²				
	2) Duration: 6 msec				
	3) Test direction: 6 directions				
	4) Number of test: 3 times per direction (18 times in total)				
5.6.	Measurements shall be made after testing under the	-			
Vibration resistance	following conditions.				
	1) Vibration frequency range: 10 to 55 Hz				
	2) Amplitude: 1.5 mm (peak-to-peak)				
	3) Sweep ratio: 10-55-10 Hz in approx. 1 min.	ESUA			
	4) Frequency sweep mode: Logarithmic or Liner sweep	1/3/0			
	5) Direction of vibration: 3 orthogonal directions including	(11.May)			
	the direction of operation.	\\$\\ 2016			
	6) Duration: 2 hr each (6 hr in total)	34			
	-, =	WO NEERING			

File number 1806

5. Mechanical Characteristics

Item	Test conditions	Criteria
5.7. Solderability	Measurements shall be made under the following conditions. 1) Solder temperature: 230 +/- 5 dig-C 2) Dipping time: 3 +/- 0.5 sec. 3) Composition of solder: Sn-3.0Ag-0.5Cu 4) Soldering flux: Rosin 25%, Alcohol 75%	More than 75% of dipped part shall be covered with solder.
5.8. Soldering heat resistance	 Hand soldering 1-1) Temperature of soldering iron tip: 350 +/- 5 degrees C 1-2) Soldering time: 3 +1/-0 seconds 1-3) The soldering iron should be applied to the terminals. 1-4) Excessive load should not be applied. 1-5) Power of the soldering iron should not exceed 15 W. Measurements shall be made after reflow soldering under 	There shall be no abnormality such as marked looseness, drop-off, and assured 4. Electrical Characteristics.
	the following conditions. 2-1) Heating method: Far-infrared radiation heating 2-2) Temperature profile: As shown in below. 2-3) Allowable soldering process: 2 times Max. Temp. (deg-C) 260 230 180 150 90+/-30 sec Fig. 8: Reflow soldering profile Time (sec)	Operating force: Item 5.1.
	The condition mentioned above is a temperature on the PWB surface on which parts are mounted. There are cases where board's temperature greatly differs from switch's surface temperature, depending on board's material, size, thickness, etc.Please care, therefore, should be used not to allow switch's surface temperature to exceed 260°C. The above temperature profile is the conditions for heat resistance test. Therefore, conditions of soldering shall be confirmed under actual production conditions.	11.May 2016

5.9. Precautions for soldering

- 1) Do not overheat when you solder with soldering iron.
- 2) Following the soldering process, do no try to clean the switch with a solvent or the like.
- 3) Safeguard the switch assembly against flux penetration from its top side.
- 4) As the conditions vary somehow on the kind of reflow soldering equipment, please make sure you have the right one before use.
- 5) As the click ratio may deteriorate when a high heat load is applied, reflow soldering should be performed in the shortest period and at the lowest temperature possible.
- 6) Please use the proper amount of solder in order to prevent the flux penetration into the switch.
- 7) Switch terminals and PWB upper face shall be free from flux prior to soldering.
- 8) Note that if the load is applied to the terminals during soldering it might cause deformation and defects in electrical performance.

File number

1806

6. Durability

6. Durability		
Item	Test conditions	Criteria
6.1.	Measurements shall be made after testing under the	Contact
Operating life	following conditions.	resistance:
	1) Electrical load:DC12V 50mA	20 ohm Max.
	2) Rate of operation: 2 cycles/sec.	
	3) Depression: The maximum value of specified operating	Insulation
	force.	resistance:
	Cycles of operation: Specified on the product specification.	10 M-ohm Min.
	5) Push rod:Material: Stainless steel Φ4.0Flat	Withstanding
		voltage:
		Item 4.3.
		Bounce
		(ON/OFF):
		20 msec Max.
		Operating force Within +/-30% of specified initial value.
		Travel:
		Item 5.3.

7. Environmental

Item	Test conditions	Criteria
7.1.	Following the test set forth below the sample shall be left in	Contact
Humidity	normal temperature and humidity conditions for 1 hr before	resistance:
resistance	measurements are made.	1 ohm Max.
	Water drops shall be removed.	
	1) Temperature: 65+/-2 deg-C, Humidity: 90 to 96% RH	Insulation
	2) Duration: 96+/-5 hr	resistance:
		10 M-ohm Min.
7.2.	Following the test set forth below the sample shall be left in	
Heat	normal temperature and humidity conditions for 1 hr before	Withstanding
resistance	measurements are made.	voltage:
	1) Temperature: 85+/-3 deg-C	Item 4.3.
	2) Duration: 96+/-5 hr	
		Bounce
7.3.	Following the test set forth below the sample shall be left in	(ON/OFF):
Cold resistance	normal temperature and humidity conditions for 1 hr before measurements are made.	20 msec Max.
	Water drops shall be removed.	Operating force:
	1) Temperature: -40+/-3 deg-C	Within +/-30%
	2) Duration: 96+/-5 hr	of specified
		initial value.
		Travel:
	SSUF	Item 5.3.

File number

1806

CTRIC. CO., LTD. S-0115

7. Environmental

Item	Test conditions	Criteria
7.4.	Following continuous 5 cycles of the temperature cycling test	Contact
Temperature	set forth below, the sample shall be left in normal	resistance:
cycling	temaperature and humidity conditions for 1hr before	1 ohm Max.
	measurements are made.	
		Insulation
		resistance:
	85+/-2 deg-	10 M-ohm Min.
		Withstanding
	-40+/-3 deg-	voltage:
	120 min 120 min	Item 4.3.
	10 to 15 min	Davisas
	10 to 15 min	Bounce
	10 to 13 111111	(ON/OFF):
	1 cycle	20 msec Max.
		Operating force
		Within +/-30%
	Fig. 9: Temperature cycling test conditions	of specified
	Fig. 9. Temperature cycling test conditions	initial value.
		iiililai value.
		Travel:
		Item 5.3.

8. Use Condition

- 8.1. Operating temperature range: Refer to the item 1.2. (Temperature range which the product is ON and OFF electrically.) There shall be no freezing and condensation.
- 8.2. Using environment
 - 1) Do not expose the products to corrosive gas such as sulfur gas and salty wind.
 - 2) Visible dust must be cleared.
 - 3) Please do not apply excessive load to the products to avoid deformation and deterioration.

9. Storage Condition

- 9.1. Storage temperature range: Refer to the item 1.3. There shall be no freezing and condensation.
- 9.2. Environment
 - 1) Do not expose the products to corrosive gas such as sulfur gas, and salty wind.
 - 2) Visible dust must be cleared.
 - 3) Please do not apply excessive load to the products to avoid deformation and deterioration.
- 9.3. Storage method
 - 1) Products shall be packed in an airtight plastic bag and stored in cool place avoiding direct sunshine.
 - 2) Do not stack too many switches for strafe. Shall be free from high temperature and high humidity.
 - 3) Do not store the products in the state of applying load on it's operation area.
 - 4) Products should be used within six months after the date of delivery.

File number

1806

- 10. Precautions in Use
- 10.1. Do not clean the products with a solvent or the like.
- 10.2. Do not use the products with beyond the rated current and voltage.
- 10.3. Do not apply excessive load to the terminals and the operating part.
- 10.4. Larger static load than specified and/or shock shall not be applied to the operating part.
- 10.5. After mounting the products on PWB/FPC, please do not stack too many PWB/FPC in order to avoid excessive load to the switch mounted area.
- 10.6. The dimensions of a pattern on PWB/FPC shall refer to the recommended dimensions in Product specifications.
- 10.7. Use of organic acid flux shall be avoided because it may cause corrosion of the switch. Please make sure the type of flux before you use it.
- 10.8. As this switch is designed for reflow soldering, if you place it at the edge of PWB for convenience, then flux may get into the sliding part of the switch during automatic dip soldering after being mounted, so do not apply auto dip after being mounted.
- 10.9. If the switch is given stress from the side, the cover may drop off and it may result in damages to switch functions. Therefore, please handle it with extreme care.
- 10.10. The operating part should be moved to the appointed position in order to ensure proper operation.
- 10.11. If you use this product in one of the following environmental conditions, progress of sulfaration and oxidization on the contact part (silver) will be accelerated, which may cause contact failure. Therefore, be careful about the operation environment.
 - 1) Around a sulfarate hot spring where sulfide gas is generated.
 - 2) In case this product is always used in a place where exhaust gas from automobiles exist.
- 10.12. Unless provided for otherwise, the products have been designed and manufactured for application in equipment and devices which are sold to end users in the market, including audio-visual equipment, electrical home appliances, office machines, information and communication equipment, and amusement equipment.
 The products are not intended for use in, and must not be used for, any application for nuclear equipment, driving equipment for aerospace or any other unauthorized use.
 With the exception of the abovementioned prohibited applications, please contact us (MITSUMI) and/or evaluate the total system regarding applicability for applications involving high levels of safety and liability such as medical equipment, burglar alarm equipment, disaster prevention equipment and undersea equipment.
 Please also incorporate fail-safe design, protection and redundant circuitry, malfunction protection, and/or fire protection into the complete system to ensure safety and reliability of the total system.
- 10.13. If you intend to use the products for automotive, please let us know beforehand.
- 10.14. If you push the edge of stem, the switch might not operate properly. An actuator to push the stem of switch in device case needs to be designed to touch the whole surface of the stem evenly.

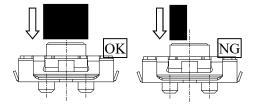


Fig. 10



File number

1806

11. Packing Specification

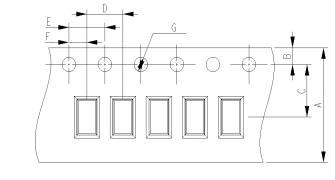
11.1. Dimensions of carrier tape are as shown below.

11.2. Taping rule

- 1) Tape winding direction is in clockwise.

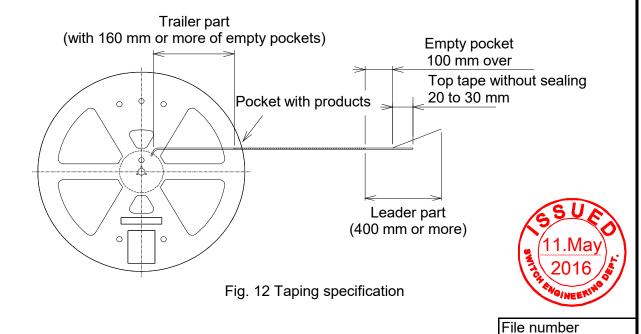
 (When pulling the tape toward, feeding holes should be located on the right side.)
- (When pulling the tape toward, feeding holes should be located on the right side2) Feeding holes shall not be covered with the cover tape.The cover tape shall not be run off the edge of the carrier tape.
- 3) 160 mm or more from the end of trailer tape part shall be empty.
- 4) The leader part shall be 400 mm or more and it should include 100 mm of empty part. The leader part shall have 20 to 30 mm of un-sealed cover tape.
- 5) The top tape of the leader part shall be stuck on the side of the reel by 30 to 50 mm using adhesive tape.
- 6) Peeling strength of cover tape from carrier tape is 0.1 to 1.3 N at 165 to 180 deg.
- 7) Bar-code label and Mitsumi label shall be stuck on the side of the reel.
- 8) The products shall free drop from the reversed carrier tape without cover tape after pressing at 0.1 to 0.2 N force.
- 9) Continuous two missing switches shall not be allowed.

 Total number of missing switches shall be 0.1% or less of the packed quantity per reel.
- 10) Switch shall be packed in single direction.
- 11) 5,000 switches shall be packed in a reel.

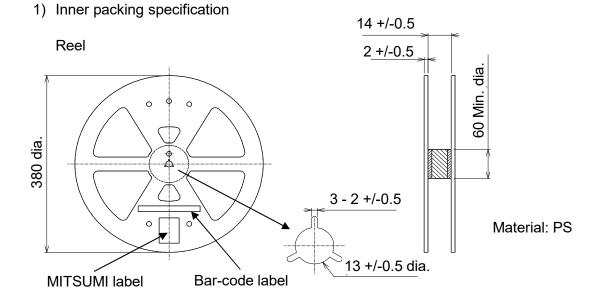


Α	В	С	D	E	F	G
12	1.75	5.5 +/-0.1	8+/-0.1	4+/-0.1	2+/-0.1	dia.1.5

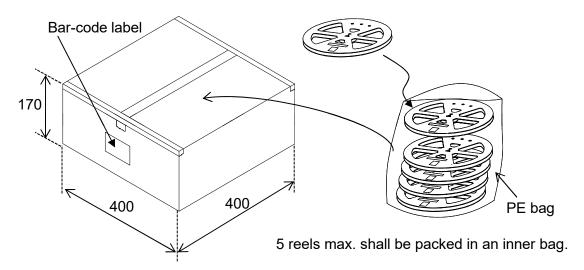
Fig. 11 Carrier tape dimensions



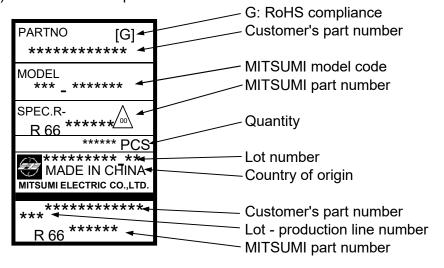
12. Packing Specification



2) Outer box specification



3) MITSUMI label specification





File number 1806